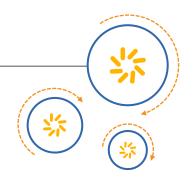


RF360 Europe GmbH

A Qualcomm - TDK Joint Venture



SAW components

BAW filter

WLAN 2G

Series/type: B8857

Ordering code: B39242B8857L210

Date: June 16, 2016

Version: 2.0

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BAW filter WLAN 2G

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2442 MHz

Data sheet

BAW filter

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BAW filter 2442 MHz

Data sheet

1 Application

- Premium-performance low-loss BAW RF single filter for Bluetooth/WLAN with LTE Band 7 / Band 40 / Band 41 coexistence
- Usable passband 79.0 MHz
- Unbalanced to unbalanced operation
- Filter impedance 50 Ω
- High out of band selectivity
- Excellent insertion loss

2 Features

- Package size 1.1 mm × 0.9 mm
- Package height 0.6 mm
- Approximate weight 1 mg
- RoHS compatible
- Package for Surface Mount Technology (SMT)
- Ni/Au-plated terminals
- Electrostatic Sensitive Device (ESD)
- Moisture Sensitivity Level 3 (MSL3)

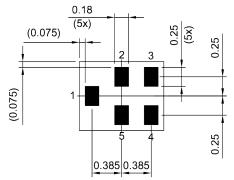


BAW filter 2442 MHz

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3 Package

BOTTOM VIEW



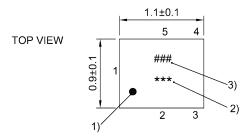
Pad and pitch tolerance ±0.05

4 Pin configuration

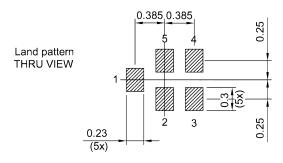
- 1 Input (to PA (unbalanced))
- 4 Output (to ANT (unbalanced))
- 2, 3, 5 Ground

SIDE VIEW





- 1) Marking for pad number 1
- 2) Encoded lot number
- 3) Please refer to caption below



Landing pad tolerance -0.02

Figure 1: Drawing of package with encoded number ###=8MS (for B8857) and package height A = 0.7 mm (max.). See Sec. Package information (p. 17).



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5 Matching circuit

■ $L_{p1} = 12 \text{ nH}$

■ $L_{p4} = 12 \text{ nH}$

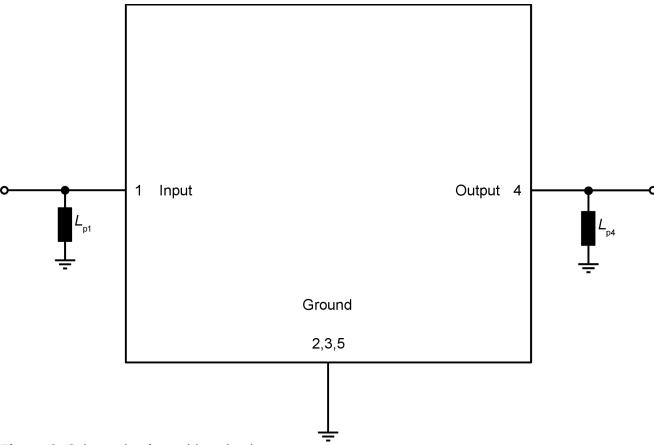


Figure 2: Schematic of matching circuit.



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6 Characteristics

Temperature range for specification $T_{\rm SPEC} = -30~{\rm ^{\circ}C}~...~+85~{\rm ^{\circ}C}$ Input terminating impedance $Z_{\rm IN} = 50~\Omega$ with par. 12 nH $^{1)}$ Output terminating impedance $Z_{\rm OUT} = 50~\Omega$ with par. 12 nH $^{1)}$

Characteristics				$\begin{array}{c} \text{min.} \\ \text{for } T_{\text{SPEC}} \end{array}$	typ. @+25 °C	$\begin{array}{c} \text{max.} \\ \text{for } T_{\text{\tiny SPEC}} \end{array}$	
Center frequency			f _C	_	2442	_	MHz
Maximum insertion attenuation			α_{max}				
Channel 1	2403.1 2420.9	MHz		_	1.6 ²⁾	2.4 ²⁾	dB
Channel 2	2408.1 2425.9	MHz		_	1.42)	2.0 ²⁾	dB
Channel 3-10	2413.1 2465.9	MHz		_	1.32)	1.82)	dB
Channel 11	2453.1 2470.9	MHz		_	1.32)	1.82)	dB
Channel 12	2458.1 2475.9	MHz		_	1.42)	2.02)	dB
Channel 13	2463.1 2480.9	MHz		_	1.62)	2.5 ²⁾	dB
Maximum VSWR			VSWR _{max}				
@ input port	2403.1 2420.9	MHz		_	1.3	2.34)	
	2420.9 2480.9	MHz		_	1.5	2.3	
@ output port	2403.1 2420.9	MHz		_	1.3	2.3 ⁴⁾	
	2420.9 2480.9	MHz		_	1.6	2.3	
Minimum attenuation			$\boldsymbol{\alpha}_{\text{min}}$				
	100 1805	MHz		31	35	_	dB
	1805 2170	MHz		33	37	_	dB
	2300 2360	MHz		45 ⁵⁾	52 ⁵⁾	_	dB
	2360 2365	MHz		445)	53 ⁵⁾	_	dB
	2365 2370	MHz		445)	50 ⁵⁾	_	dB
	2370 2380	MHz		325)	495)	_	dB
	2496 2501	MHz		19 ^{5), 6)}	435)	_	dB
	2500 2505	MHz		45 ^{5), 6)}	64 ⁵⁾	_	dB
	2505 2550	MHz		45 ⁵⁾	495)	_	dB
	2550 2570	MHz		42 ⁵⁾	46 ⁵⁾	_	dB
	2570 2620	MHz		405)	445)	_	dB
	2620 2690	MHz		39 ⁵⁾	435)	_	dB
	4800 5805	MHz		25	33	_	dB
	7200 7500	MHz		20	27	_	dB

See Sec. Matching circuit (p. 5).

²⁾ Averaged value within each Wifi channel width of 17.8 MHz.

³⁾ +25°C.

⁴⁾ +10°C to +85°C.

⁵⁾ Averaged values of linear S-parameter over any 5MHz.

^{6) +25°}C to +85°C.



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7 **Maximum ratings**

Storage temperature	T _{STG} ¹⁾ = −40 °C +90 °C	
DC voltage	$V_{DC} = 5.0 \text{ V}^{5)}$	
ESD voltage		
	$V_{\rm ESD}^{2)} = 50 \rm V$	Machine model.
	$V_{ESD}^{3)} = 300 \text{ V}$	Human body model.
	V _{ESD} ⁴⁾ = 600 V	Charged device model.
Input power	P _{IN}	
@ input port: 2403.1 2480.9 MHz (WLAN channel 1 to channel 13)	24 dBm	20MHz OFDM signal for 5000 h @ 65 °C.

²⁾

Not valid for packaging material. Storage temperature for packaging material -25 to +40 °C.

According to JESD22-A115B (MM – Machine Model), 10 negative & 10 positive pulses.

According to JESD22-A114F (HBM – Human Body Model), 1 negative & 1 positive pulse.

According to JESD22-C10C (CDM – Field Induced Charged Device Model), 3 negative & 3 positive pulses.

¹⁶⁸h Damp Heat Steady State acc. to IEC60068-2-67 Cy.



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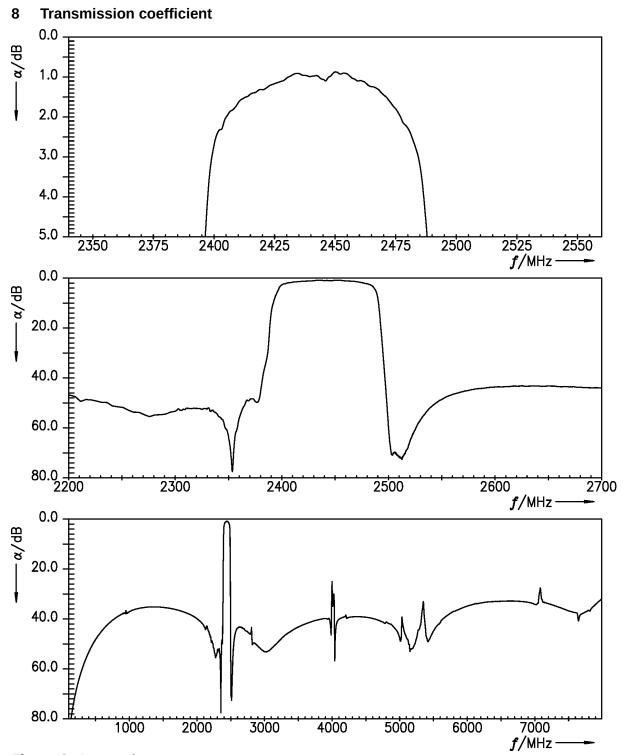


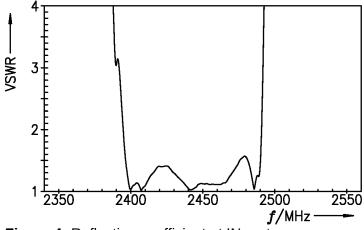
Figure 3: Attenuation.



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9 Reflection coefficients



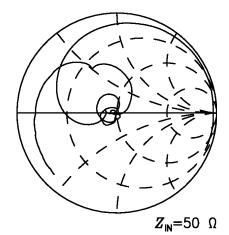
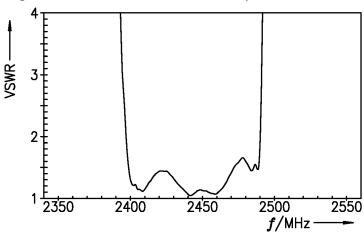


Figure 4: Reflection coefficient at IN port.



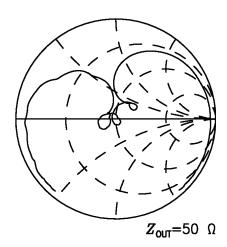


Figure 5: Reflection coefficient at OUT port.

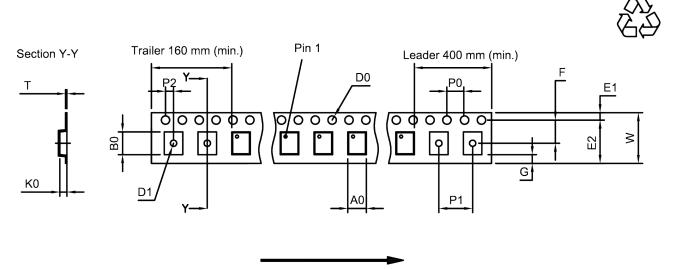


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10 Packing material

10.1 Tape



User direction of unreeling

Figure 6: Drawing of tape (first-angle projection) with tape dimensions according to Table 1.

A ₀	1.1±0.05 mm	E ₂	_	 Pı	2.0±0.1 mm
B ₀	1.3±0.05 mm	F	3.5±0.05 mm	P ₂	2.0±0.05 mm
D ₀	1.5 mm	G	_	Т	0.25±0.03 mm
D_1	0.4±0.05 mm	K_0	0.76±0.03 mm	 W	8.0±0.1 mm
E ₁	1.75±0.1 mm	P ₀	4.0±0.1 mm		

Table 1: Tape dimensions.



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10.2 Reel with diameter of 180 mm

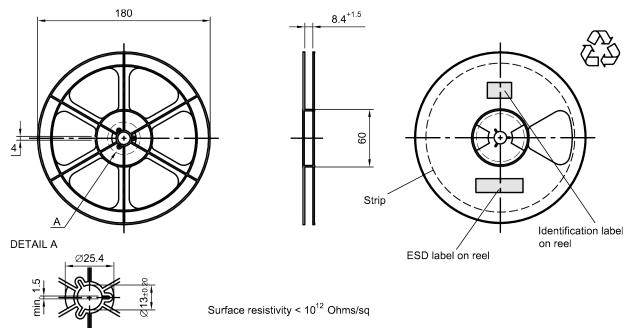


Figure 7: Drawing of reel (first-angle projection) with diameter of 180 mm.

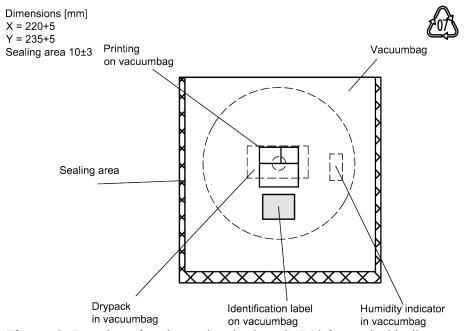


Figure 8: Drawing of moisture barrier bag (MBB) for reel with diameter of 180 mm.



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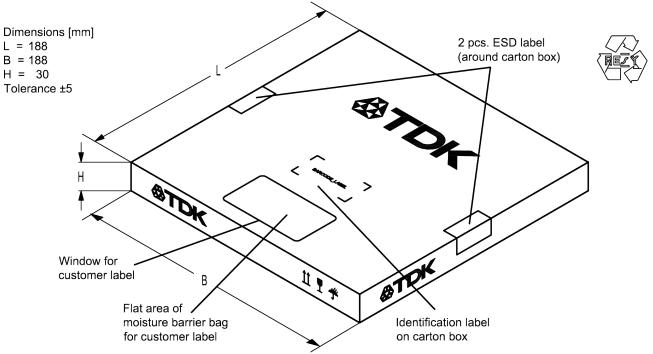


Figure 9: Drawing of folding box for reel with diameter of 180 mm.

10.3 Reel with diameter of 330 mm

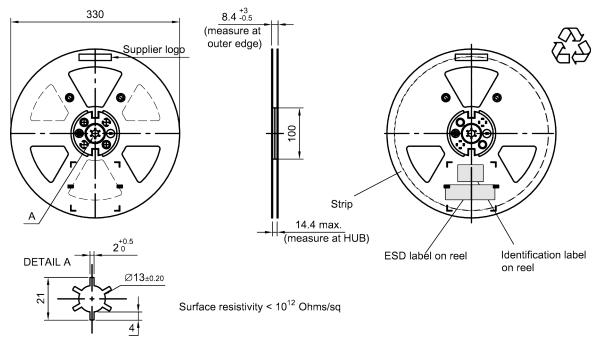


Figure 10: Drawing of reel (first-angle projection) with diameter of 330 mm.



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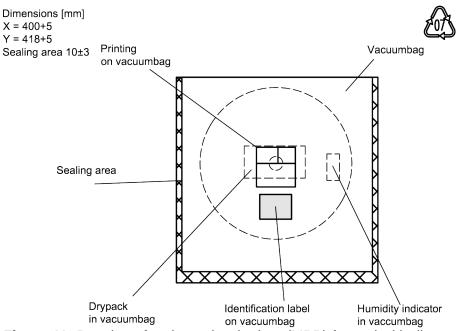


Figure 11: Drawing of moisture barrier bag (MBB) for reel with diameter of 330 mm.

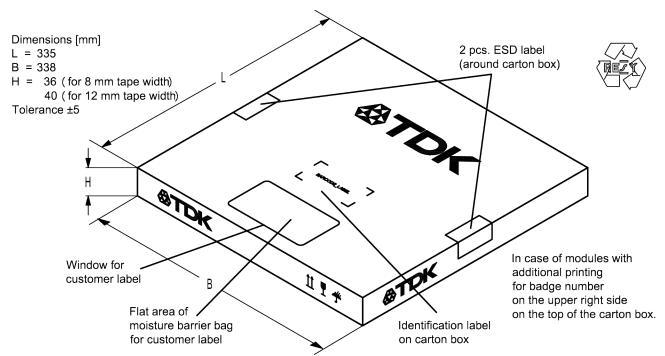


Figure 12: Drawing of folding box for reel with diameter of 330 mm.

11 Marking

Products are marked with product type number and lot number encoded according to Table 2:

■ Type number:



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The 4 digit type number of the ordering code, e.g., B3xxxxB1234xxxx, is encoded by a special BASE32 code into a 3 digit marking.

Example of decoding type number marking on device in decimal code.

16J => 1234 $1 \times 32^2 + 6 \times 32^1 + 18 = 1234$

The BASE32 code for product type B8857 is 8MS.

■ Lot number:

The last 5 digits of the lot number, e.g., are encoded based on a special BASE47 code into a 3 digit marking.

Example of decoding lot number marking on device in decimal code.

5UY => 12345 5 \times 47² + 27 (=U) \times 47¹ + 31 (=Y) \times 47⁰ = 12345

Adopted BASE32 code for type number				
Decimal	Base32	Decimal	Base32	
value	code	value	code	
0	0	16	G	
1	1	17	Н	
2	2	18	J	
3	3	19	K	
4	4	20	М	
5	5	21	N	
6	6	22	Р	
7	7	23	Q	
8	8	24	R	
9	9	25	S	
10	Α	26	Т	
11	В	27	V	
12	С	28	W	
13	D	29	X	
14	E	30	Υ	
15	F	31	Z	

Adopted BASE47 code for lot number				
Decimal	Base47	Decimal	Base47	
value	code	value	code	
0	0	24	R	
1	1	25	S	
2	2	26	Т	
3	3	27	U	
4	4	28	V	
5	5	29	W	
6	6	30	X	
7	7	31	Υ	
8	8	32	Z	
9	9	33	b	
10	Α	34	d	
11	В	35	f	
12	С	36	h	
13	D	37	n	
14	E	38	r	
15	F	39	t	
16	G	40	V	
17	Н	41	\	
18	J	42	?	
19	K	43	{	
20	L	44	}	
21	М	45	<	
22	N	46	>	
23	Р			

Table 2: Lists for encoding and decoding of marking.



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12 Soldering profile

The recommended soldering process is in accordance with IEC $60068-2-58-3^{rd}$ edit and IPC/JEDEC J-STD-020B.

ramp rate	≤ 3 K/s
preheat	125 °C to 220 °C, 150 s to 210 s, 0.4 K/s to 1.0 K/s
T > 220 °C	30 s to 70 s
T > 230 °C	min. 10 s
T > 245 °C	max. 20 s
<i>T</i> ≥ 255 °C	-
peak temperature T_{peak}	250 °C +0/-5 °C
wetting temperature T_{min}	230 °C +5/-0 °C for 10 s ± 1 s
cooling rate	≤ 3 K/s
soldering temperature <i>T</i>	measured at solder pads

Table 3: Characteristics of recommended soldering profile for lead-free solder (Sn95.5Ag3.8Cu0.7).

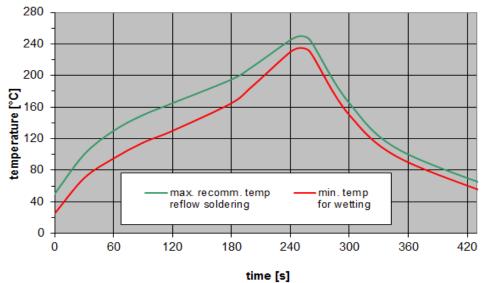


Figure 13: Recommended reflow profile for convection and infrared soldering – lead-free solder.



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13 Annotations

13.1 Matching coils

See TDK inductor pdf-catalog http://www.tdk.co.jp/tefe02/coil.htm#aname1 and Data Library for circuit simulation http://www.tdk.co.jp/etvcl/index.htm.

13.2 RoHS compatibility

ROHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011, on the restriction of the use of certain hazardous substances in electrical and electronic equipment ("Directive") with due regard to the application of exemptions as per Annex III of the Directive in certain cases.

13.3 Scattering parameters (S-parameters)

The pin/port assignment is available in the headers of the S-parameter files. Please contact your local EPCOS sales office.

13.4 Ordering codes and packing units

Ordering code	Packing unit
B39242B8857L210	15000 pcs
B39242B8857L210S 5	5000 pcs

Table 4: Ordering codes and packing units.



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14 Cautions and warnings

14.1 Display of ordering codes for EPCOS products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications and the website of EPCOS, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products. Detailed information can be found on the Internet under www.epcos.com/orderingcodes.

14.2 Material information

Due to technical requirements components may contain dangerous substances. For information on the type in question please also contact one of our sales offices.

For information on recycling of tapes and reels please contact one of our sales offices.

14.3 Moldability

Before using in overmolding environment, please contact your local EPCOS sales office.

14.4 Package information

Landing area

The printed circuit board (PCB) land pattern (landing area) shown is based on EPCOS internal development and empirical data and illustrated for example purposes, only. As customers' SMD assembly processes may have a plenty of variants and influence factors which are not under control or knowledge of EPCOS, additional careful process development on customer side is necessary and strongly recommended in order to achieve best soldering results tailored to the particular customer needs.

Dimensions

Unless otherwise specified all dimensions are understood using unit millimeter (mm).

Projection method

Unless otherwise specified first-angle projection is applied.



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